



Product Features: Low Cost SMD Package RoHs Compliant Compatible with Leadfree Processing	Applications: Fibre Channel Server & Storage Sonet /SDH 802.11 / Wifi T1/E1, T3/E3 System Clock	→ 12.5 Max. -→ 9.4 →		
Frequency	3.5 MHz to 35 MHz			
ESR (Equivalent Series Resistance) 3.5 MHz – 3.99 MHz 4.0 MHz – 5.99 MHz 6.0 MHz – 9.99 MHz 10.0 MHz – 35 MHz	200 Ω Max. 150 Ω Max. 100 Ω Max. 50 Ω Max.			
Shunt Capacitance (C0)	7 pF Max.	└───┛ ╶╾┥ ┝╾		
Frequency Tolerance @ 25° C	\pm 30 ppm Standard (see Part Number Guide for more options)	4.6 Max.		
Frequency Stability over Temperature	\pm 50 ppm Standard (see Part Number Guide for more options)			
Crystal Cut	AT Cut	Our and the Disease		
Load Capacitance	18 pF Standard (see Part Number Guide for more options) Connection Diagram			
Drive Level	1 mW Max.			
Aging	±5 ppm Max. / Year Standard	Ц <u></u>		
Temperature		- → - 1.8		
Operating	0° C to +70° C Standard (see Part Number Guide for more options)			
Storage	-40° C to +85° C Standard	1.8		

Part Number Guide		Sample Part Number:	IL3S - FB1F18	- 20.000		
Package	Stability (ppm) at Room Temperature	Stability (ppm) over Operating Temperature	Operating Temperature Range	Mode (overtone)	Load Capacitance (pF)	Frequency
IL3S -	B = ±50 ppm	$B = \pm 50 \text{ ppm}$	$0 = 0^{\circ}C \text{ to } +50^{\circ}C$	F = Fundamental	18 pF Standard. Or Specify	- 20.000 MHz
	F = ±30 ppm	F = ±30 ppm	1 = 0°C to +70°C			
	G = ±25 ppm	G = ±25 ppm	2 = -10°C to +60°C			
	H = ±20 ppm	H = ±20 ppm	3 = -20°C to +70°C			
	l = ±15 ppm	I = ±15 ppm**	5 = -40°C to +85°C			
	J = ±10 ppm*	J = ±10 ppm**	9 = -10°C to +50°C			

* Not available at all frequencies. ** Not available for all temperature ranges.

ILSI America Phone: 775-851-8880 • Fax: 775-851-8882 • e-mail: e-mail@ilsiamerica.com • www.ilsiamerica.com Specifications subject to change without notice

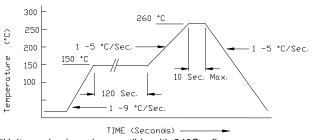


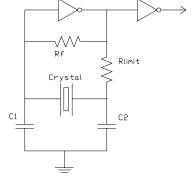
4 Pad Plastic Package Quartz Crystal, 4.6 mm x 12.5 mm



Pb Free Solder Reflow Profile:

Typical Circuit:





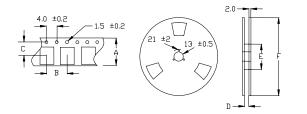
*Units are backward compatible with 240C reflow processes

Package Information:

MSL = 2a

Termination = e1 (Sn/Cu/Ag over Ni over Kovar base metal)

Tape and Reel Information:



Quantity per Reel	1000
A	24 +/3
В	12 +/2
С	11.5 +/2
D	25 +/-1.5
E	80 / 100
F	330

Environmental Specifications

Thermal Shock	MIL-STD-883, Method 1011, Condition A
Moisture Resistance	MIL-STD-883, Method 1004
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Mechanical Vibration	MIL-STD-883, Method 2007, Condition A
Resistance to Soldering Heat	J-STD-020C, Table 5-2 Pb-free devices (except 2 cycles max)
Hazardous Substance	Pb-Free / RoHS / Green Compliant
Solderability	JESD22-B102-D Method 2 (Preconditioning E)
Terminal Strength	MIL-STD-883, Method 2004, Test Condition D
Gross Leak	MIL-STD-883, Method 1014, Condition C
Fine Leak	MIL-STD-883, Method 1014, Condition A2, R1=2x10-8 atm cc/s
Solvent Resistance	MIL-STD-202, Method 215

Marking

Line 1: I- Frequency